

Product Change Notice

Micron PCN: 30542 Date: 10/31/2011

Type of Change: Die Shrink, End of Life

Title of Change: 137b T69M based MCP's EOL/Die Shrink

Description of Change: 50nm 137b T69M based MCP's will be replaced with either 42nm T79M DRAM

shrink or 42nm DRAM and 25nm NAND shrink.

The DRAM only shrink will support chipsets that can accommodate 4bit ECC. The DRAM and NAND shrink will support chipsets that can accommodate 8bit

ECC.

Reason for Change: Better align industry standards, Optimization of Manufacturing Efficiency

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Product Affected: 137b T69M based MCP's

Affected Micron Part Number	Replacement - 4bit ECC	Replacement - 8bit ECC
MT29C4G48MAYAPAKD-5 IT	MT29C4G48MAYBAAKS-5 WT	MT29C4G48MAAGBAAKS-5 WT
MT29C4G48MAYAPAKD-6 IT	MT29C4G48MAYBAAKS-5 WT	MT29C4G48MAAGBAAKS-5 WT
MT29C4G48MAZAPAKD-5 E IT	none	none
MT29C4G48MAZAPAKD-5 IT	MT29C4G48MAZBAAKS-5 WT	MT29C4G48MAAHBAAKS-5 WT
MT29C4G48MAZAPAKD-6 IT	MT29C4G48MAZBAAKS-5 WT	MT29C4G48MAAHBAAKS-5 WT
MT29C4G96MAYAPCJA-5 IT	MT29C4G96MAYBACKD-5 WT	MT29C4G96MAAGBACKD-5 WT
MT29C4G96MAZAPCJA-5 E IT	none	none
MT29C4G96MAZAPCJA-5 IT	MT29C4G96MAZBACKD-5 WT	MT29C4G96MAAHBACKD-5 WT
MT29C4G96MAZAPCJA-6 IT	MT29C4G96MAZBACKD-5 WT	MT29C4G96MAAHBACKD-5 WT
MT29C8G96MAYAPDJA-5 IT	MT29C8G96MAYBADKD-5 WT	MT29C8G96MAAEBACKD-5 WT
MT29C8G96MAYAPDJA-6 IT	MT29C8G96MAYBADKD-5 WT	MT29C8G96MAAEBACKD-5 WT
MT29C8G96MAZAPDJA-5 IT	MT29C8G96MAZBADKD-5 WT	MT29C8G96MAAFBACKD-5 WT
MT29C8G96MAZAPDJA-6 IT	MT29C8G96MAZBADKD-5 WT	MT29C8G96MAAFBACKD-5 WT

Micron Sites Affected: All Sites

42nm T79M Based Product

Sample Availability Date: Dec 2011 Qual Data Availability Date: Jan 2012 Product Ship Date: Feb 2012

50nm T69M Based Product

Last Time Buy: 1-Jun-2012 Last Time Ship: 1-Dec-2012